

1 2 3 4 5 6 7 8

A

B

C

D

E

F

A

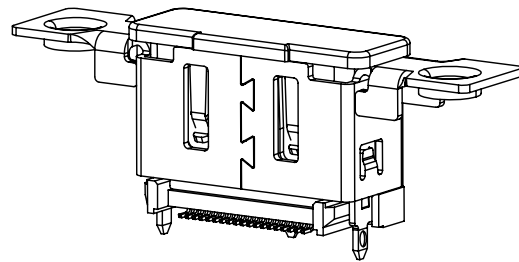
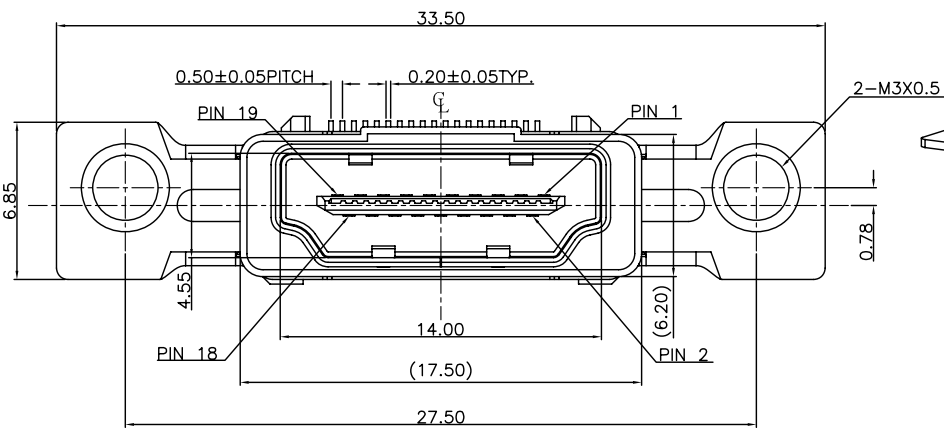
B

C

D

E

F

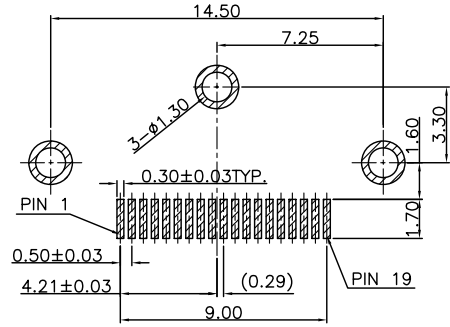
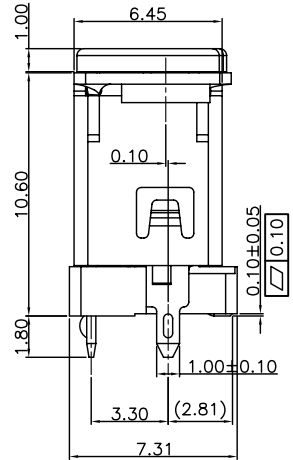
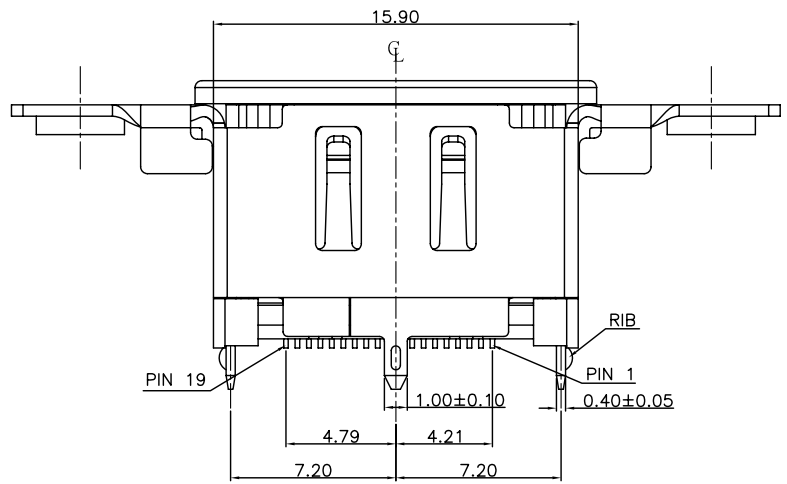


3D VIEW

NOTES:

- 1. MATERIAL:
 - 1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL 94V-0 RATED, BLACK
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 SHELL: COPPER ALLOY/SPCC
- 2. PLATING:
 - 2.1 CONTACT:
GOLD PLATED OVER NICKEL
 - 2.2 SHELL:
NICKEL PLATED
- 3. P/N: HHF-33X000-XSB

TERMINAL PLATING CODE: _____ REV. CODE _____
 A: CONTACT AREA: GOLD FLASH
 SOLDER AREA: MATTE TIN 100u"
 B: CONTACT AREA: 3u" GOLD
 SOLDER AREA: MATTE TIN 100u"
 C: CONTACT AREA: 15u" GOLD
 SOLDER AREA: MATTE TIN 100u"



RECOMMENDED PCB LAYOUT THICKNESS = 1.6 mm

**TOLERANCE = ±0.05
(TOP VIEW)**

MATERIAL	TOLERANCE UNSPECIFIED	ZheJiang HeFeng Technology Co.,Ltd	SCALE	UNIT
	0.0 ±0.30 0°. ±2'		1:1	mm
	0.00 ±0.20 .0° ±1'		NAME	
	0.000 ±0.10 .0° ±0.5'		HDMI A/F 朝天式 SMT TYPE	
FINISH	DRAWN 孙洪桥 09/05/25	DRAWING NO. HHF-33X000-XSB	SHEET	
	DESIGNER 孙洪桥 09/05/25		1/2	
	CHECKED			
	APPROVED		REV A	

A	新版发行	chu	2010-12-05
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期

1 2 3 4 5 6 7 8